

CHEMICALLY-AMPLIFIED POSITIVE PHOTSENSITIVE RESIN
COMPOSITION, MANUFACTURING METHOD OF SUBSTRATE WITH
CASTING MOLD, AND MANUFACTURING METHOD OF ELECTROPLATED
MOLDED ARTICLE

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ABSTRACT OF THE DISCLOSURE

A chemically-amplified positive photosensitive resin composition with excellent sensitivity and rectangularity, a manufacturing method of a substrate with a casting mold, and a manufacturing method of an electroplated molded article are provided.

10 The chemically-amplified type positive photosensitive resin composition contains a resin (A) containing an acid-dissociated protecting group and obtained by polymerizing a monomer mixture, a novolac resin (B), a photoacid generator (C), and a solvent (D). In particular, the novolac resin (B) is obtained by a polycondensation of cresol aromatic hydroxyl compound and an aldehyde compound, and based on an integral area of 100%
15 of a molecular weight of the novolac resin (B) measured by gel permeation chromatography, a cresol binuclear area of the novolac resin (B) is between 0.5% and 6%.

Fig. 1